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SEMICONDUCTOR INTEGRATED CIRCUIT

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[There are no amendments to this patent.]

Claim

A semiconductor integrated circuit characterized by a construction in which semiconductor integrated circuit device (2) is packaged between the substrate for semiconductor integrated circuit packaging and semiconductor integrated circuit device (1), thereby increasing the packaging density with the connection process of the semiconductor integrated circuit (1) and the substrate for packaging and, at the same time, by sealing the semiconductor integrated circuit (2) using a sealing material attached to the semiconductor integrated circuit (1).

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